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GROUP 1700

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Sun et al.

Serial No.: 09/755,717

Confirmation No.: 5164

Filed: January 5, 2001

For: TANTALUM REMOVAL
DURING CHEMICAL
MECHANICAL
POLISHING

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Group Art Unit: 1765

Examiner: Lan Vinh

Mail Stop
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CERTIFICATE OF MAILING	
37 CFR 1.8	
I hereby certify that this correspondence is being deposited on <u>July 1, 2003</u> with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.	
<u>July 1, 2003</u> Date	<u>Edgar D. J. Jr.</u> Signature

Dear Sir:

RESPONSE TO OFFICE ACTION DATED APRIL 1, 2003

In response to the Office Action dated April 1, 2003 having a shortened statutory period for response set to expire on July 1, 2003. Please enter this response and reconsider the claims pending in the application for reasons discussed below. Although Applicants believe that no fee is due in connection with this response, the Commissioner is hereby authorized to charge counsel's Deposit Account No. 20-0782/AMAT/5538/EJS, for any fees, including extension of time fees or excess claim fees, required to make this response timely and acceptable to the Office.

IN THE CLAIMS:

27. A method for selective removal of a tantalum-comprising layer from a substrate in chemical mechanical polishing, comprising: